

[54] POLYPHEYLENE ETHER-RESIN  
COMPOSITIONS WITH  
ORGANOPOLYILOXANES HAVING  
SILICON-H-BONDS

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[22] Filed: Feb. 8, 1974

[21] Appl. No.: 440,759

[52] U.S. Cl. .... 260/874; 260/45.7 R;  
260/47 ET; 260/827; 260/824 R; 260/876 R

[51] Int. Cl.<sup>2</sup> ..... C08L 71/04; C08L 25/06;  
C08L 83/06

[58] Field of Search..... 260/827, 874, 45.7 R,  
260/824 R, 47 ET

[57] ABSTRACT

Thermoplastic compositions which comprise a poly-  
phenylene ether resin, an alkenyl aromatic resin and a  
organopolysiloxane having Si—H bonds are disclosed.  
These compositions have good thermal stability in that  
they resist discoloration when processed in a thermal  
cycle.

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16 Claims, No Drawings